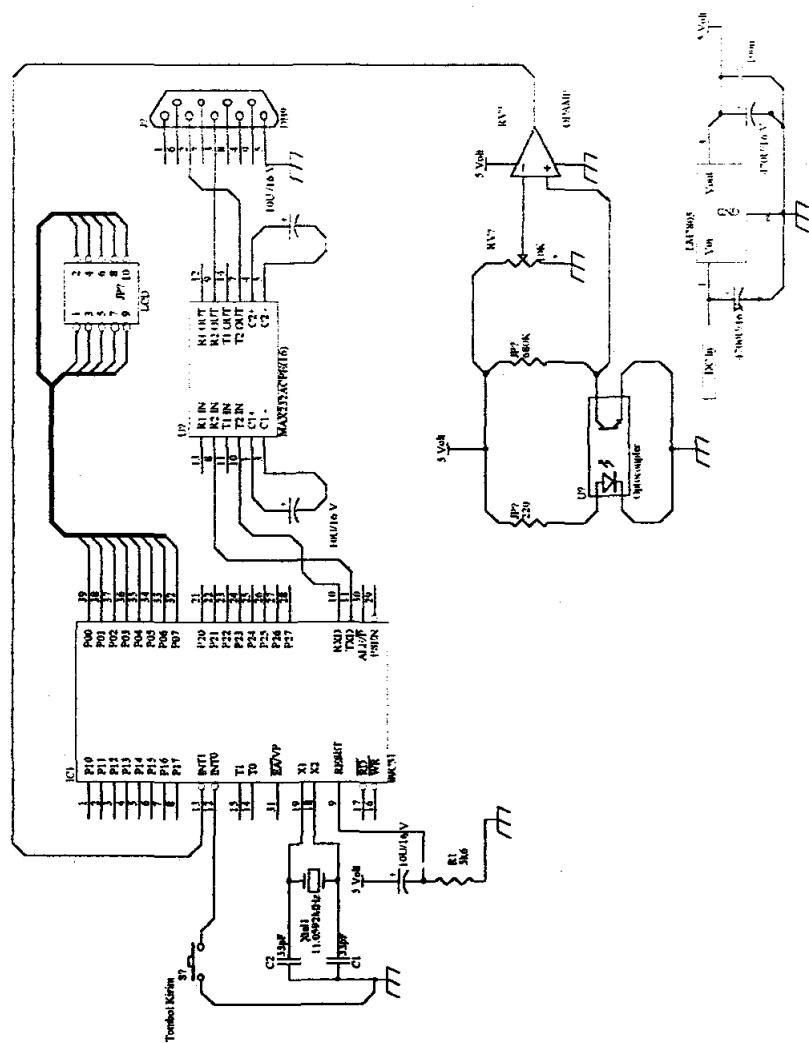


LAMPIRAN



```

uses dos,crt,GRAPH;
const TX = $3F3;
      RX = $3F5;
      LCR = $3FB;
      MSB = $3F9;
      LSB = $3F6;
      IER = $3F8;
      LSR = $3FD;
      MCR = $3FC;
      IIR = $3FA;
      ACO = $20;
      AO1 = $21;
Gray50 : FillPatternType = (SAA, $55, SAA,
$55, SAA, $55, SAA, $55);

var r:registers;
    rev:pointer;
    TOM:CHAR;
    data_ok,read_ok:boolean;
    n,serial,pointer:byte;
    gd,gm:integer;
    data:array[0..10]of byte;
    temp_meteran,meteran:longint;
    s:string[12];
    pentol:string[9];

PROCEDURE INITSER;
BEGIN
    PORT[LCR]:=128;
    PORT[MSB]:=0;
    PORT[LSB]:=12;
    PORT[LCR]:=7;
    PORT[IER]:=1;
    PORT[AO1]:=32;
    PORT[LSR]:=0;
    PORT[MCR]:=$F;
END;

FUNCTION DATA_IN:BOOLEAN;
BEGIN
    IF PORT[IIR]=4 THEN DATA_IN:=TRUE ELSE DATA_IN:=FALSE;
END;
FUNCTION TX_KOSONG:BOOLEAN;
BEGIN
    IF PORT[LSR]=96 THEN TX_KOSONG:= TRUE ELSE TX_KOSONG:=FA
LSE;
END;

function IntToStr(I:longint):string;
var

```

```

S: string[11];
begin
Str(I,S);
IntToStr :=S;
end;

PROCEDURE SEND(DATA:BYTE);
BEGIN
IF TX_KOSONG THEN PORT[TX]:=DATA;
delay(10);
END;

PROCEDURE RECEIVER;INTERRUPT;
BEGIN
IF DATA_IN THEN
BEGIN
if not(read_ok) then
begin
serial:=PORT[RX];
data[pointer]:=serial;
inc(pointer);
if pointer=7 then
begin
meteran:=data[3]+256*data[4]+65536*data[5]+167
77216*data[6];
meteran:=meteran div 36;
read_ok:=true;
end;
end;
END;
PORT[A00]:=$20;
END;

BEGIN
Gd := Detect;
InitGraph(Gd, Gm, ' ');
if GraphReSult <> grOk then Halt(1);
clrscr;
getIntvec($c,rev);
setIntvec($c,@receiver);
initser;
repeat
if read_ok then
begin
cleardevice;
setbkcolor(black);
SetTextStyle(1,0,7);
setColor(white);
outtextxy(120,90,'Pemakaian :');
SetFillPattern(Gray50,blue);

```

```
bar(20,170,600,300);
s:='0000,0000M';
temp_meteran:=meteran;
for n:=9 downto 1 do
begin
  if n>5 then
    begin
      pentol:=inttostr(temp_meteran mod 10);
      s[n]:=pentol[1];
      temp_meteran:=temp_meteran div 10;
    end;
  end;
SetTextStyle(1,0,7);
setcolor(yellow);
outtextxy(90,170,s);
SetTextStyle(1,0,5);
setcolor(yellow);
outtextxy(530,160,'3');
pointer:=0;
read_ok:=false;
end;
if keypressed then tom:=readkey;
until tom=#27;
setintvec($c,rev);
closegraph;
end.
```

COUNT	EQU	08H	
TEMP1	EQU	09H	
TEMP2	EQU	0AH	
TEMP3	EQU	0BH	
TEMP4	EQU	0CH	
IN1	EQU	0DH	
IN2	EQU	0EH	
IN3	EQU	0FH	
IN4	EQU	10H	
VAR6	EQU	11H	;VARIABLE 64 BIT
VAR7	EQU	12H	
VAR8	EQU	13H	
VAR9	EQU	14H	
VAR10	EQU	15H	
VAR11	EQU	16H	
VAR12	EQU	17H	;MSB 64 BIT
VAR1	EQU	18H	;LSB 32 BIT
VAR2	EQU	19H	
VAR3	EQU	1AH	
VAR4	EQU	1BH	;MSB 32 BIT
FREE	EQU	1CH	
SELECT	EQU	1DH	
VAR5	DATA	21H	;LSB 64 BIT
VOLUME	EQU	30H	;4 BYTES
DETIK	EQU	34H	
MENIT	EQU	35H	
JAM	EQU	36H	
DAY	EQU	37H	
VOLUME_DISP	EQU	38H	; 4 BYTES
prescaler	EQU	3ch	; 4 bytes
lcd_buff_ln1	EQU	40H	;16 BYTES
lcd_buff_ln2	EQU	50H	;16 BYTES
PRESS	BIT	0	
UPDATE	BIT	1	
BLANK	BIT	2	
CLOCK	BIT	3	
STAT_BLINK	BIT	4	
	ORG	00H	
	AJMP	MULAI	
	ORG	0BH	
	AJMP	TMRO	
	ORG	13H	
	AJMP	INT1	
	ORG	30H	

;		TIMER0	

```

;-----
tmr0      ajnz    prescaler,esc_tmr0
          mov     prescaler,#30
          djnz   prescaler+1,esc_tmr0
          mov     prescaler+1,#20
          djnz   prescaler+2,esc_tmr0
          mov     prescaler+2,#3
          cpl    stat_blink
          jz     stat_blink,esc_tmr0
          setb   clock
esc_tmr0  reti

```

```

;-----  
; PULSA OPTO
;-----
```

```

INT1      PUSH    A
          INC     VOLUME
          MOV    A,VOLUME
          JNZ    RUTIN_UPDATE
          INC    VOLUME-1
          MOV    A,VOLUME+1
          JNZ    RUTIN_UPDATE
          INC    VOLUME-2
          MOV    A,VOLUME-2
          JNZ    RUTIN_UPDATE
          INC    VOLUME-3
RUTIN_UPDATE JB     UPDATE,ESC_INT1
              MOV    VOLUME_DISP,VOLUME
              MOV    VOLUME_DISP+1,VOLUME+1
              MOV    VOLUME_DISP+2,VOLUME+2
              MOV    VOLUME_DISP+3,VOLUME+3
              SETB   UPDATE
ESC_INT1    POP    A
              RETI

```

```

;-----  
; DELAY 4 mS
;-----
```

```

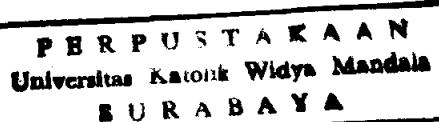
delay4m    mov    r7,#50
del4m     mov    r6,#250
          djnz  r6,$
          djnz  r7,del4m
          ret

```

```

;-----  
; delay data lcd
;-----  
del_lcd    mov    a,#200
          djnz  a,$
          ret

```



```

;-----
;    enable pulse
;-----
enable      anl      a,#0fh
            ani      p0,#0f0h
            orl      p0,a
            clr      p0.5
            seto    p0.5
            clr      p0.5
            mov      a,#10
            djnz   a,s
            ret

;-----
;    CONTROL LCD
;-----
lcdcontrol  mov      free,a
            swap   a
            acall  enable
            mov    a,free
            acall  enable
            acall  del_lcd
            ret

;-----
;    inisialisasi lcd
;-----
initlcd4bit  clr      p0.4
            mov      r5,#10
wait_lcd     mov      a,#3
            acall  enable
            acall  delay4m
            djnz   r5,wait_lcd

WAITFUNCT    mov      a,#2
            acall  enable
            acall  delay4m

            mov      a,#2fh          ;FUNCTIONSET
            acall  lcdcontrol
            mov      a,#0ch          ;DISPLAY ON
            acall  lcdcontrol
            mov      a,#01h          ;DISPLAY CLEAR
            acall  lcdcontrol
            mov      a,#06h          ;ENTRY
            acall  lcdcontrol
            ret

;-----
```

```

; DISPLAY LCD
;-----
lcd      setb    p0.4
         mov     free,a
         swap   a
         acall  enable
         acall  del_lcd
         mov    a,free
         acall  enable
         clr    p0.4
         ret

;-----
; PEMBAGIAN
;-----
BAGI      MOV     A,R0
         PUSH   A
         MOV     A,R1
         PUSH   A
         MOV     A,R2
         PUSH   A
         MOV     IN1,VAR1
         MOV     IN2,VAR2
         MOV     IN3,VAR3
         MOV     IN4,VAR4
         MOV     VAR1,#0
         MOV     VAR2,#0
         MOV     VAR3,#0
         MOV     VAR4,#0
         MOV     COUNT,#64

BAGI1    CLR     C
         MOV     A,VAR5          ;GESER LSB 64 BIT
         RLC     A
         MOV     VAR5,A
         MOV     R0,#11H          ;ALAMAT VAR6
         MOV     R2,#11
         MOV     A,@R0          ;GESER KIRI
         RLC     A
         MOV     @R0,A
         INC     R0
         DJNZ   R2,SHIFT
         MOV     TEMP1,VAR1
         MOV     TEMP2,VAR2
         MOV     TEMP3,VAR3
         MOV     TEMP4,VAR4
         CLR     C          ;PENGURANGAN
         MOV     R0,#18H
         MOV     R1,#0DH
         MOV     R2,#4

```

```

KURANG      MOV     A, @R0
              SUBB    A, @R1
              MOV     @R0, A
              INC     R0
              INC     R1
              DJNZ   R2, KURANG
              JC    CLEAR_VARBIT0 ;CEK APAKAH RESULT

NEGATIVE    SETB    VAR5.0
              AJMP    CEKCOUNTER

CLEAR_VARBIT0 MOV     VAR1, TEMP1
                MOV     VAR2, TEMP2
                MOV     VAR3, TEMP3
                MOV     VAR4, TEMP4
CEKCOUNTER  DJNZ   COUNT, BAGI1
              POP    A
              MOV    R2, A
              POP    A
              MOV    R1, A
              POP    A
              MOV    R0, A
              RET

;-----;
;          PERKALIAN
;-----;

KALI        MOV     IN1, VAR1
              MOV     IN2, VAR2
              MOV     IN3, VAR3
              MOV     IN4, VAR4
              MOV     VAR9, #0
              MOV     VAR10, #0
              MOV    VAR11, #0
              MOV    VAR12, #0
              MOV    VAR1, #0
              MOV    VAR2, #0
              MOV    VAR3, #0
              MOV    VAR4, #0
              MOV    COUNT, #32

KALI1       CLR     C
              JNB    VAR5.0, PASS2 ;APAKAH Q0 = 0 ?
              MOV    R0, #18H
              MOV    R1, #0DH
              MOV    R2, #4
TAMBAH      MOV    A, @R0
              ADDC  A, @R1
              MOV    @R0, A
              INC    R0

```

```

        INC      R1
        DJNZ    R2,TAMBAH
PASS2      MOV      R0,#1BH          ;ALAMAT VAR6
        MOV      R2,#4
SHIFTR1    MOV      A,@R0           ;GESER KANAN
        RRC      A
        MOV      @R0,A
        DEC      R0
        DJNZ    R2,SHIFTR1
        MCV      R0,#13H
        MOV      R2,#3
SHIFTR2    MOV      A,@RC
        RRC      A
        MOV      @R0,A
        DEC      RC
        DJNZ    R2,SHIFTR2
        MOV      A,VAR5           ;GESER LSB 64 BIT
        RRC      A
        MOV      VAR5,A
        DJNZ    COUNT,HALI1       ;APAKAH COUNTER =
0 ?
        MOV      VAR12,VAR4
        MOV      VAR11,VAR3
        MOV      VAR10,VAR2
        MOV      VAR9,VAR1
        RET

;-----;
;PROTOCOL DISPLAY 16 CHAR
;-----;
protocol_lcd   mov      r0,a
                mov      free,#16
next_protocol  mov      a,#0
                movc    a,@a+dptra
                inc     dptra
                push   dph
                push   dpl
                push   free
                mov    @r0,a
                inc     r0
                pop    free
                pop    dpl
                pop    dph
                djnz   free,next_protocol
                ret

;-----;
; MAPING MEMORY TO LCD
;-----;
map_buff      mov      a,#80h

```

```

        acall    lcdcontrol
        mov      r0,#lcd_buff_ln1
        mov      r7,#16
        mov      a,@r0
        disp_11 acall    lcd
        inc      r0
        djnz   r7,disp_11

        mov      a,#0c0h
        acall    lcdcontrol
        mov      r0,#lcd_buff_ln2
        mov      r7,#16
        disp_12 mov      a,@r0
        acall    lcd
        inc      r0
        djnz   r7,disp_12
        ret

;-----
;      delay 1 secon
;-----
delay      mov      a,#7
delay2     mov      r7,#250
delay1     mov      r6,#250
        djnz   r6,s
        djnz   r7,delay1
        djnz   a,delay2
        ret

;-----
;      IDENTITY
;-----
IDENTITY   MOV      DPTR,#NAMA
            MOV      A,#LCD_BUFF_LN1
            ACALL   PROTOCOL_LCD
            MOV      DPTR,#NRP
            MOV      A,#LCD_BUFF_LN2
            ACALL   PROTOCOL_LCD
            ACALL   MAP_BUFF
            ACALL   DELAY
            RET
NAMA       DB      ' GO KIANG DJOEN '
NRP        DB      ' 51030960XX '

;-----
;      BACKGROUND
;-----
BACKGROUND  MOV      DPTR,#BACKGROUND2
            MOV      A,#LCD_BUFF_LN2
            ACALL   PROTOCOL_LCD

```

```

        RET
BACKGROUND2    DB      'TOTAL:   ,'

;-----
;     ALU ACTIV 4 BYTES
;-----
ACTIV_4BYTE    MOV     VAR9, #0
                MOV     VAR10, =1
                MOV     VAR11, =1
                MOV     VAR12, =1
                RET

;-----
;     DISP BCD METER AIR
;-----
DISP_BCD       MOV     VAR1, #11
                MOV     VAR2, =0
                MOV     VAR3, =0
                MCV     VAR4, =0
                ACALL   BAGI
                MOV     A, VAR1
                ORL     A, #30H
                MOV     @R0, A
                DEC     R0
                DJNZ    R7, DISP_BCD
                RET

;-----
;     routine baris 1
;-----
baris1         mov     a, detik
                mov     b, #60
                div     ab
                mov     detik, b ;detik
                add     a, menit ;menit
                mov     b, #60
                div     ab
                mov     menit, b
                add     a, jam ;jam
                mov     b, #24
                div     ab
                mov     jam, b
                add     a, day ;hari
                mov     b, #7
                div     ab
                mov     day, b

                mov     r0, #jam ;load jam to buffer
r lcd          mov     r1, #lcd_buff_ln1+8

```

```

bcd_adjust      mov    r7,#3
                 mov    a,@r0
                 mov    b,#10
                 div    ab
                 orl    a,#30h
                 orl    b,#30h
                 mov    @r1,a
                 inc    r1
                 mov    @r1,b
                 inc    r1
                 inc    r1
                 dec    r0
                 djnz   r7,bcd_adjust
                 mov    lcd_buff_ln1+8+2,#3ah
                 mov    lcd_buff_ln1+8+5,#3ah

r_lcd           mov    dptr,#hari          ;load day to buffer

                 mov    a,day
                 mov    b,=6
                 mul    ab
                 add    a,dpl
                 mov    dpl,a
                 mov    a,#0
                 addc   a,dph
                 mov    dph,a
                 mov    r0,#lcd_buff_ln1
                 mov    r7,#8

get_char_hari   mov    a,#0
                 movc   a,@a+dptr
                 mov    @r0,a
                 inc    dptr
                 inc    r0
                 djnz   r7,get_char_hari
                 inc    detik
                 ret

hari            db    'Senin '
                 db    'Selasa '
                 db    'Rabu '
                 db    'Kamis '
                 db    'Jumat '
                 db    'Sabtu '
                 db    'Minggu '

;----- MAIN PROGRAM -----
;----- MULAI          MOV    SP,#60H
;-----                  ACALL INITLCD4BIT

```

	ACALL	IDENTITY
	CLR	PRESS
	MOV	R0,#VOLUME
	MOV	R7,#11
RESET_VALUE	MOV	@R0,#0
	INC	R0
	DJNZ	R7,RESET_VALUE
	MOV	R0,#VOLUME_disp
RESET_Volume	MOV	R7,#4
	MOV	@R0,#0
	INC	R0
	DJNZ	R7,RESET_VOLUME
	MOV	prescaler+2,#3
	MOV	DETIK,#0
	MOV	MENIT,=48
	MOV	JAM,#10
	mov	select,#0
	MOV	TMOD,#22H
	MOV	SCON,=50H
	MOV	PCON,#80H
	MOV	TL1,=0FAH
	MOV	TH1,#0FAH
	SETB	TR1
	MOV	TLO,#64
	MOV	TH0,#64
	SETB	TR0
	SETB	IT1
	MOV	IE,#86H ;ACTIF INT1 & TMRO
	SETB	UPDATE
DISP_METER_AIR	JNB	UPDATE,RUTIN_JAM
	acall	background
	MOV	VAR5,VOLUME_DISP
	MOV	VAR6,VOLUME_DISP+1
	MOV	VAR7,VOLUME_DISP+2
	MOV	VAR8,VOLUME_DISP+3
	ACALL	ACTIV_4BYTE
	MOV	VAR1,#36
	MOV	VAR2,#0
	MOV	VAR3,#0
	MOV	VAR4,#0
	ACALL	BAGI
	MOV	R0,#LCD_BUFF_LN2+15
	MOV	R7,#4
	ACALL	DISP_BCD
	MOV	R0,#LCD_BUFF_LN2+10
	MOV	R7,#5
	ACALL	DISP_BCD
	JB	P1.0,esc_disp_volume

	mov	r0,#volume_disp
	mov	r7,#4
next_tx	mov	a,@r0
	mov	sbuf,a
	jnb	ti,\$
	clr	ti
	inc	r0
	djnz	r7,next_tx
esc_disp_volume	clr	update
RUTIN_JAM	jb	p0.6,cek_keyset
	jb	press,rutinCLOCK
	setb	press
	inc	select
	mov	a,select
	cjne	a,#5,rutinCLOCK
	mov	select,#0
	sjmp	rutinCLOCK
cek_keyset	jb	p0.7,no_keypress
	jb	press,rutinCLOCK
	setb	press
	mov	a,select
	jz	rutinCLOCK
	cjne	a,#1,set_mnt_jam_day ;if set detik then
detik=reset	mov	detik,#0
	sjmp	rutinCLOCK
set_mnt_jam_day	add	a,#detik-1
	mov	r0,a
	inc	@r0
	sjmp	rutinCLOCK
no_keypress	clr	press
rutinCLOCK	jnb	clock,blink
	acall	baris1
	clr	clock
	ajmp	display
blink	jnb	stat_blink,no_display
	mov	a,select
	cjne	a,#1,blink_mnt
	mov	lcd_buff_ln1+14,#20h
	mov	lcd_buff_ln1+15,#20h
blink_mnt	cjne	a,#2,blink_detik
	mov	lcd_buff_ln1+11,#20h
	mov	lcd_buff_ln1+12,#20h
blink_detik	cjne	a,#3,blink_day
	mov	lcd_buff_ln1+8,#20h

```
        mov    lcd_buff_ln1+9,#20h
- blink_day    cjne  a,#4,display
        mov    lcd_buff_ln1+0,#20h
        mov    lcd_buff_ln1+1,#20h
        mov    lcd_buff_ln1+2,#20h
        mov    lcd_buff_ln1+3,#20h
        mov    lcd_buff_ln1+4,#20h
        mov    lcd_buff_ln1+5,#20h
display      acall map_buff
no_display   ajmp DISP_METER_AIR
```

features

Compatible with MCS-51™ Products

4K Bytes of In-System Reprogrammable Flash Memory

- Endurance: 1,000 Write/Erase Cycles

Fully Static Operation: 0 Hz to 24 MHz

Three-level Program Memory Lock

128 x 8-bit Internal RAM

32 Programmable I/O Lines

Two 16-bit Timer/Counters

Six Interrupt Sources

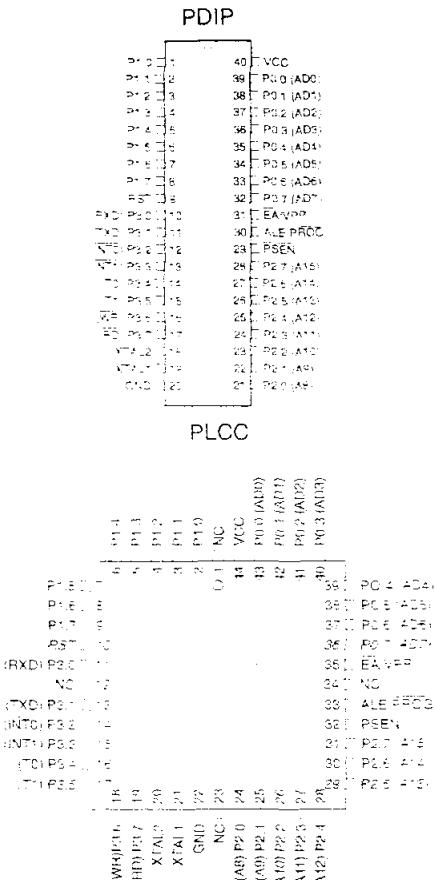
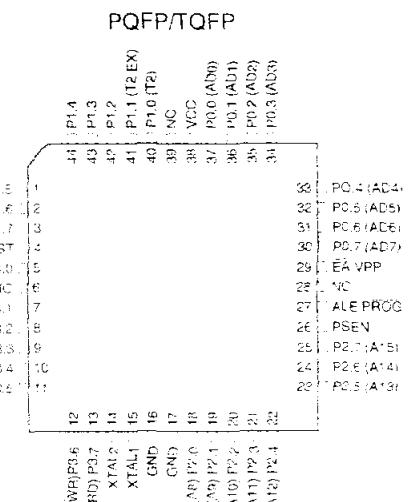
Programmable Serial Channel

Low-power Idle and Power-down Modes

Description

The AT89C51 is a low-power, high-performance CMOS 8-bit microcomputer with 4K bytes of Flash programmable and erasable read only memory (PEROM). The device is manufactured using Atmel's high-density nonvolatile memory technology and is compatible with the industry-standard MCS-51 instruction set and pinout. The on-chip flash allows the program memory to be reprogrammed in-system or by a conventional nonvolatile memory programmer. By combining a versatile 8-bit CPU with Flash in a monolithic chip, the Atmel AT89C51 is a powerful microcomputer which provides a highly-flexible and cost-effective solution to many embedded control applications.

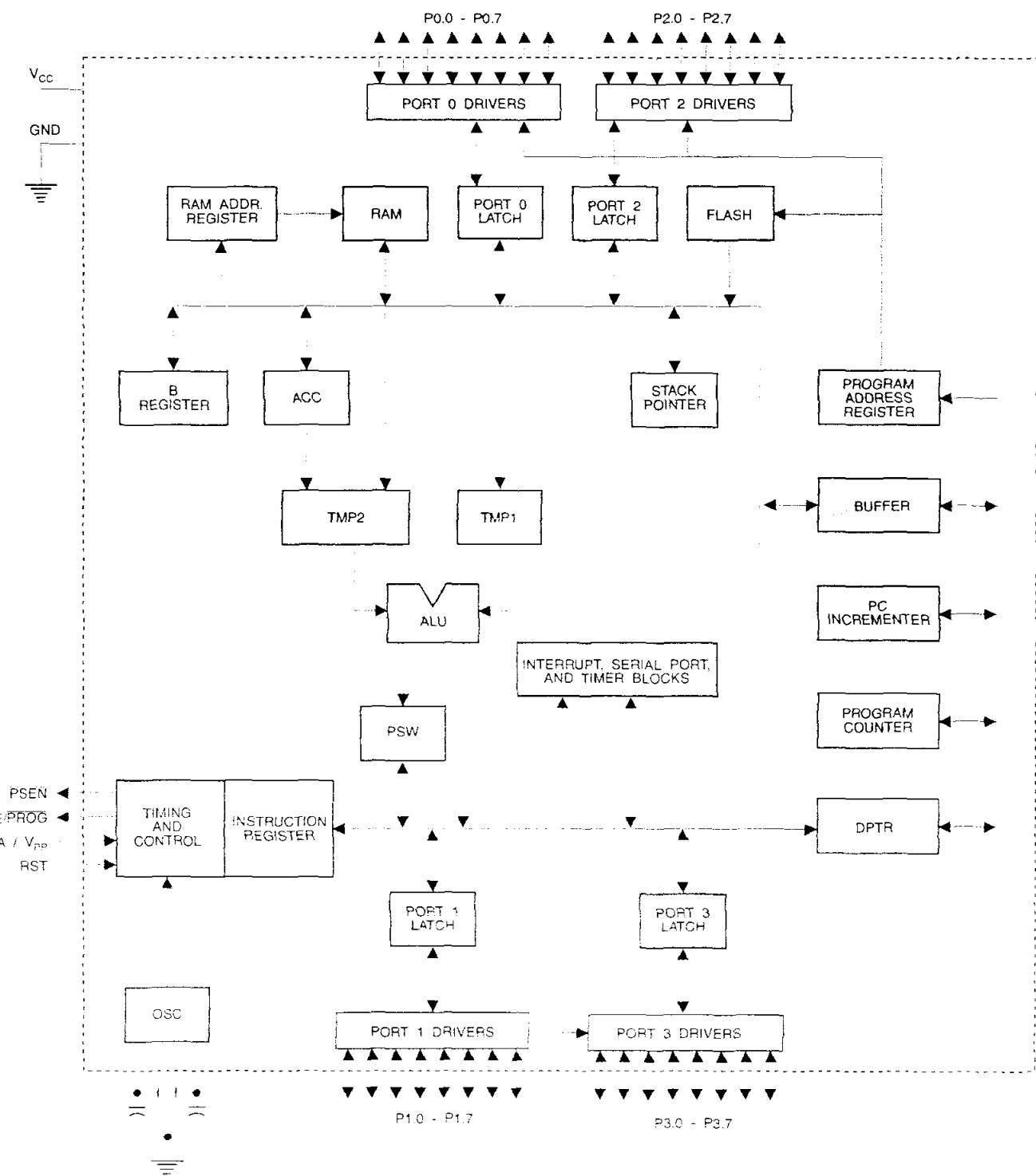
in Configurations



8-bit Microcontroller with 4K Bytes Flash

AT89C51

Block Diagram



T89C51 provides the following standard features: 4K of Flash, 128 bytes of RAM, 32 I/O lines, two 16-bit counters, a five vector two-level interrupt architecture, duplex serial port, on-chip oscillator and clock circuit. In addition, the AT89C51 is designed with static logic operation down to zero frequency and supports two user selectable power saving modes. The Idle Mode stops the CPU while allowing the RAM, timer/counters, port and interrupt system to continue functioning. The Power-down Mode saves the RAM contents but freezes the oscillator disabling all other chip functions until the next reset.

Description

voltage.

d.

is an 8-bit open-drain bi-directional I/O port. As an input port, each pin can sink eight TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 may also be configured to be the multiplexed low-address/data bus during accesses to external program and data memory. In this mode P0 has internal pullups.

Port 0 also receives the code bytes during Flash programming and outputs the code bytes during program verification. External pullups are required during program verification.

Port 1 is an 8-bit bi-directional I/O port with internal pullups. Port 1 output buffers can sink/source four TTL inputs. When 1s are written to Port 1 pins they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (I_{IL}) because of the internal pullups.

Port 1 also receives the low-order address bytes during programming and verification.

Port 2 is an 8-bit bi-directional I/O port with internal pullups. Port 2 output buffers can sink/source four TTL inputs. When 1s are written to Port 2 pins they are pulled high by the internal pullups and can be used as inputs. As inputs,

Port 2 pins that are externally being pulled low will source current (I_{IL}) because of the internal pullups.

Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application, it uses strong internal pullups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ R1), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during Flash programming and verification.

Port 3

Port 3 is an 8-bit bi-directional I/O port with internal pullups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pullups.

Port 3 also serves the functions of various special features of the AT89C51 as listed below:

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	INT0 (external interrupt 0)
P3.3	INT1 (external interrupt 1)
P3.4	T0 (timer 0 external input)
P3.5	T1 (timer 1 external input)
P3.6	WR (external data memory write strobe)
P3.7	RD (external data memory read strobe)

Port 3 also receives some control signals for Flash programming and verification.

RST

Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device.

ALE/PROG

Address Latch Enable output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input (PROG) during Flash programming.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, and may be used for external timing or clocking purposes. Note, however, that one ALE



is skipped during each access to external Data memory.

If required, ALE operation can be disabled by setting bit 0 of location 8EH. With the bit set, ALE is active only during MOVX or MOVC instruction. Otherwise, the pin is always pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.

PSEN
Program Store Enable is the read strobe to external program memory.

When the AT89C51 is executing code from external program memory, PSEN is activated twice each machine cycle except that two PSEN activations are skipped during access to external data memory.

PP

EA
External Access Enable. EA must be strapped to GND in order to enable the device to fetch code from external program memory locations starting at 0000H up to FFFFH, however, that if lock bit 1 is programmed, EA will be latched on reset.

EA should be strapped to V_{CC} for internal program locations.

The pin also receives the 12-volt programming enable voltage (V_{PP}) during Flash programming, for parts that require it V_{PP}.

C1
C1 is connected to the inverting oscillator amplifier and input to the local clock operating circuit.

C2
C2 is connected to the output of the inverting oscillator amplifier.

Oscillator Characteristics

C1 and XTAL2 are the input and output, respectively, of an inverting amplifier which can be configured for use as an on-chip oscillator, as shown in Figure 1. Either a quartz crystal or ceramic resonator may be used. To drive the oscillator from an external clock source, XTAL2 should be left

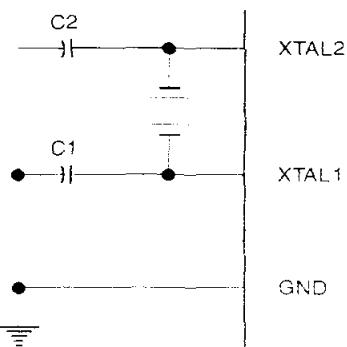
unconnected while XTAL1 is driven as shown in Figure 2. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

Idle Mode

In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the special functions registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

It should be noted that when idle is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when Idle is terminated by reset, the instruction following the one that invokes Idle should not be one that writes to a port pin or to external memory.

Figure 1. Oscillator Connections

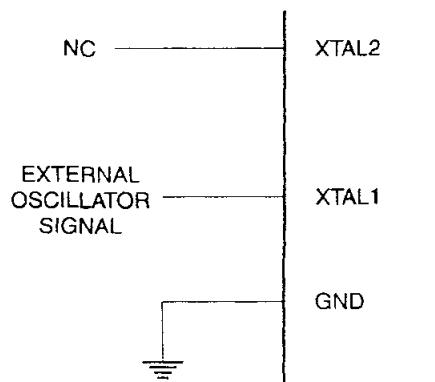


Note: C1, C2 = 30 pF ± 10 pF for Crystals
= 40 pF ± 10 pF for Ceramic Resonators

Use of External Pins During Idle and Power-down Modes

	Program Memory	ALE	PSEN	PORT0	PORT1	PORT2	PORT3
	Internal	1	1	Data	Data	Data	Data
	External	1	0	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

2. External Clock Drive Configuration



Power-down Mode

In power-down mode, the oscillator is stopped, and the instruction that invokes power-down is the last instruction executed. The on-chip RAM and Special Function Registers

retain their values until the power-down mode is terminated. The only exit from power-down is a hardware reset. Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before V_{CC} is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

Program Memory Lock Bits

On the chip are three lock bits which can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in the table below.

When lock bit 1 is programmed, the logic level at the EA pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value, and holds that value until reset is activated. It is necessary that the latched value of EA be in agreement with the current logic level at that pin in order for the device to function properly.

Lock Bit Protection Modes

Program Lock Bits				
	LB1	LB2	LB3	Protection Type
1	U	U	U	No program lock features
2	P	U	U	MOV C instructions executed from external program memory are disabled from fetching code bytes from internal memory. EA is sampled and latched on reset, and further programming of the Flash is disabled
3	P	P	U	Same as mode 2, also verify is disabled
4	P	P	P	Same as mode 3, also external execution is disabled



Programming the Flash

The AT89C51 is normally shipped with the on-chip Flash memory array in the erased state (that is, contents = FFH) ready to be programmed. The programming interface supports either a high-voltage (12-volt) or a low-voltage program enable signal. The low-voltage programming mode provides a convenient way to program the AT89C51 inside the user's system, while the high-voltage programming mode is compatible with conventional third-party Flash or EPROM programmers.

The AT89C51 is shipped with either the high-voltage or low-voltage programming mode enabled. The respective code marking and device signature codes are listed in the following table.

	$V_{PP} = 12V$	$V_{PP} = 5V$
Side Mark	AT89C51	AT89C51
	xxxx	xxxx-5
	yyww	yyww
Signature	(030H) = 1EH (031H) = 51H (032H) = F FH	(030H) = 1EH (031H) = 51H (032H) = 05H

The AT89C51 code memory array is programmed byte-by-byte in either programming mode. To program any non-byte in the on-chip Flash Memory, the entire memory must be erased using the Chip Erase Mode.

Programming Algorithm: Before programming the AT89C51, the address, data and control signals should be set according to the Flash programming mode table and Figure 3 and Figure 4. To program the AT89C51, take the following steps.

1. Set the desired memory location on the address lines.

2. Set the appropriate data byte on the data lines.

3. Activate the correct combination of control signals. Raise \overline{EA}/V_{PP} to 12V for the high-voltage programming mode.

4. Pulse ALE/PROG once to program a byte in the Flash array or the lock bits. The byte-write cycle is self-timed and typically takes no more than 1.5 ms. Repeat steps 1 through 5, changing the address

and data for the entire array or until the end of the object file is reached.

Data Polling: The AT89C51 features Data Polling to indicate the end of a write cycle. During a write cycle, an attempted read of the last byte written will result in the complement of the written datum on P0.7. Once the write cycle has been completed, true data are valid on all outputs, and the next cycle may begin. Data Polling may begin any time after a write cycle has been initiated.

Ready/Busy: The progress of byte programming can also be monitored by the RDY/BSY output signal. P3.4 is pulled low after ALE goes high during programming to indicate BUSY. P3.4 is pulled high again when programming is done to indicate READY.

Program Verify: If lock bits LB1 and LB2 have not been programmed, the programmed code data can be read back via the address and data lines for verification. The lock bits cannot be verified directly. Verification of the lock bits is achieved by observing that their features are enabled.

Chip Erase: The entire Flash array is erased electrically by using the proper combination of control signals and by holding ALE/PROG low for 10 ms. The code array is written with all "1"s. The chip erase operation must be executed before the code memory can be re-programmed.

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 030H, 031H, and 032H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows.

- (030H) = 1EH indicates manufactured by Atmel
- (031H) = 51H indicates 89C51
- (032H) = FFH indicates 12V programming
- (032H) = 05H indicates 5V programming

Programming Interface

Every code byte in the Flash array can be written and the entire array can be erased by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

All major programming vendors offer worldwide support for the Atmel microcontroller series. Please contact your local programming vendor for the appropriate software revision.

Flash Programming Modes

Mode	RST	PSEN	ALE/PROG	EA/V _{PP}	P2.6	P2.7	P3.6	P3.7
Code Data	H	L	(1)	H/12V	L	H	H	H
Code Data	H	L	H	H	L	L	H	H
Lock Bit - 1	H	L	(1)	H/12V	H	H	H	H
Lock Bit - 2	H	L	(1)	H/12V	H	H	L	L
Lock Bit - 3	H	L	(1)	H/12V	H	L	H	L
Erase	H	L	(1)	H/12V	H	L	L	L
Signature Byte	H	L	H	H	L	L	L	L

1. Chip Erase requires a 10 ms PROG pulse.

Figure 3. Programming the Flash

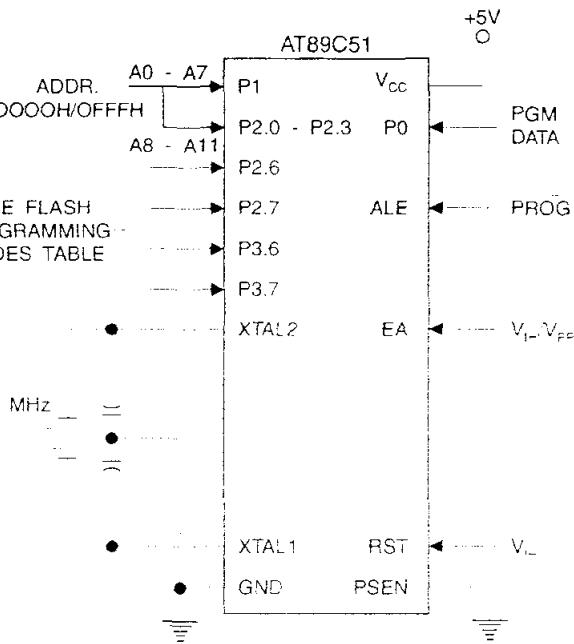
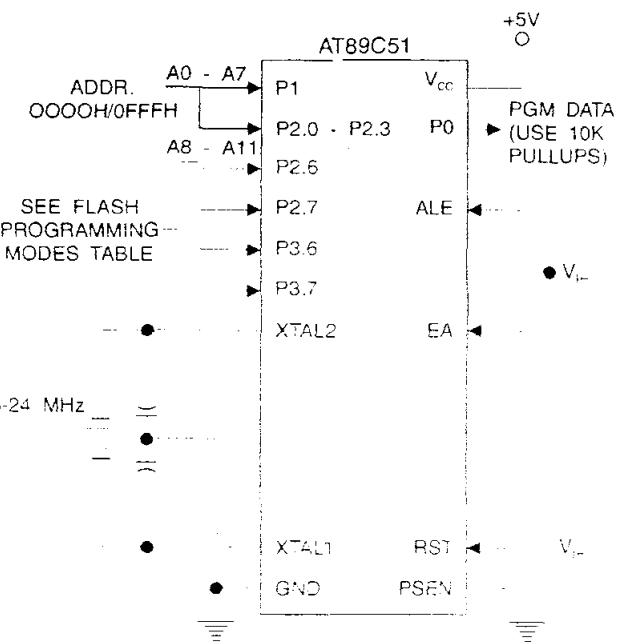
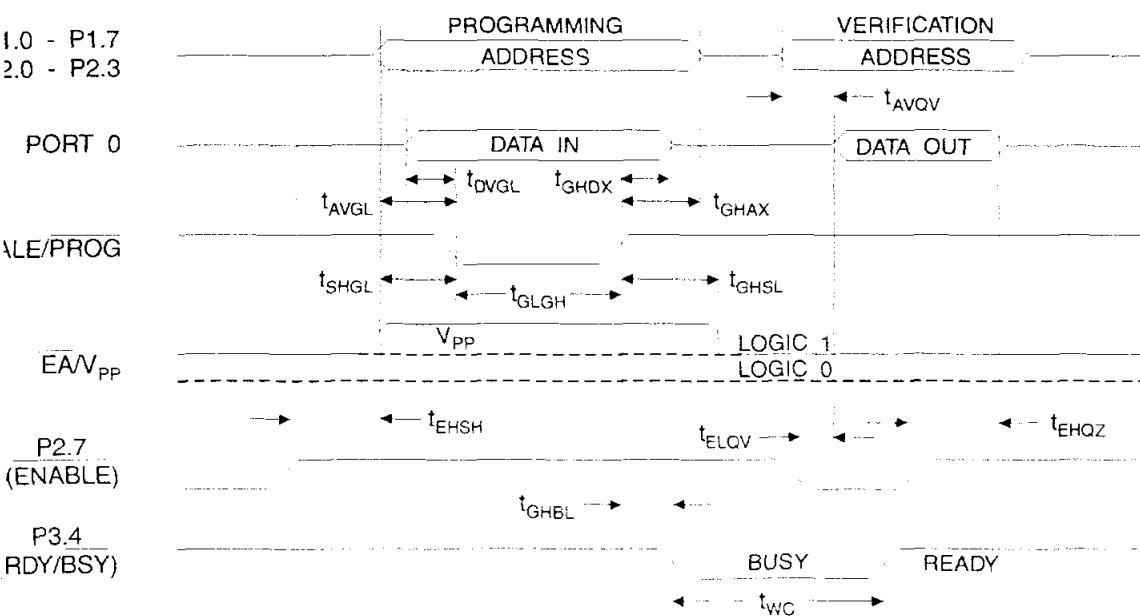


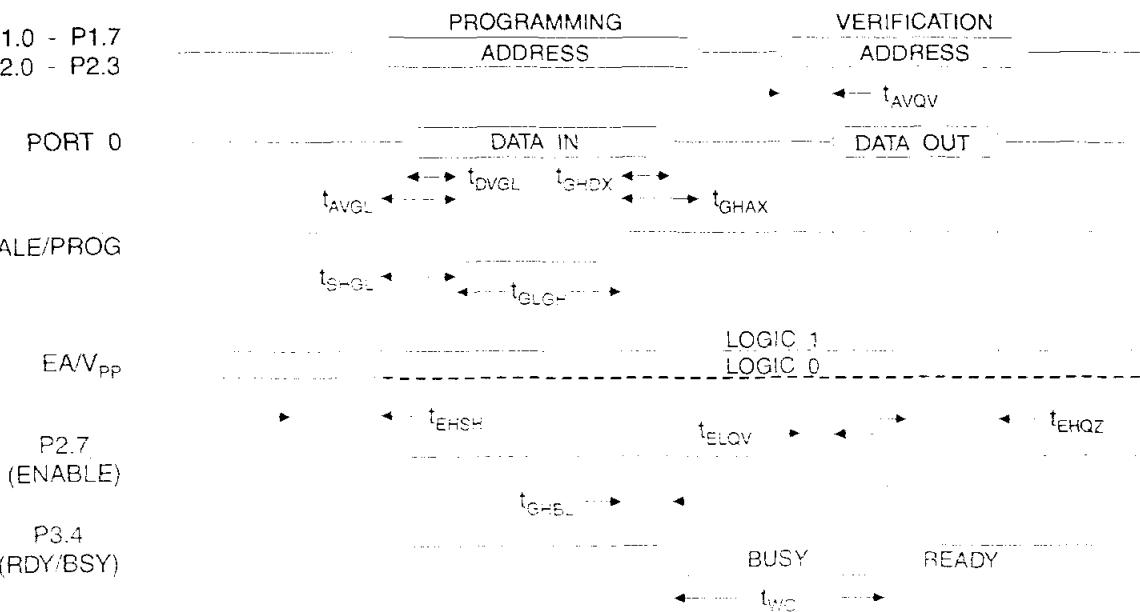
Figure 4. Verifying the Flash



h Programming and Verification Waveforms - High-voltage Mode ($V_{PP} = 12V$)



l Programming and Verification Waveforms - Low-voltage Mode ($V_{PP} = 5V$)



Programming and Verification Characteristics

°C to 70°C, $V_{CC} = 5.0 \pm 10\%$

Symbol	Parameter	Min	Max	Units
	Programming Enable Voltage	11.5	12.5	V
L	Programming Enable Current		1.0	mA
	Oscillator Frequency	3	24	MHz
	Address Setup to PROG Low	$48t_{CLCL}$		
	Address Hold After PROG	$48t_{CLCL}$		
	Data Setup to PROG Low	$48t_{CLCL}$		
	Data Hold After PROG	$48t_{CLCL}$		
	P2.7 (ENABLE) High to V_{PP}	$48t_{CLCL}$		
1)	V_{PP} Setup to PROG Low	10		μs
	V_{PP} Hold After PROG	10		μs
	PROG Width	1	110	μs
	Address to Data Valid		$48t_{CLCL}$	
	ENABLE Low to Data Valid		$48t_{CLCL}$	
	Data Float After ENABLE	0	$48t_{CLCL}$	
	PROG High to BUSY Low		1.0	μs
	Byte Write Cycle Time		2.0	ms

1. Only used in 12-volt programming mode.



Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Voltage Temperature	-65°C to +150°C
Voltage on Any Pin Respect to Ground	-1.0V to +7.0V
Maximum Operating Voltage	6.6V
Output Current	15.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Characteristics

-40°C to 85°C, $V_{CC} = 5.0V \pm 20\%$ (unless otherwise noted)

Parameter	Condition	Min	Max	Units
Input Low-voltage	(Except EA)	-0.5	0.2 V_{CC} - 0.1	V
Input Low-voltage (EA)		-0.5	0.2 V_{CC} - 0.3	V
Input High-voltage	(Except XTAL1, RST)	0.2 V_{CC} + 0.9	V_{CC} + 0.5	V
Input High-voltage	(XTAL1, RST)	0.7 V_{CC}	V_{CC} + 0.5	V
Output Low-voltage ⁽¹⁾ (Ports 1,2,3)	$I_{OL} = 1.6$ mA		0.45	V
Output Low-voltage ⁽¹⁾ (Port 0, ALE, PSEN)	$I_{OL} = 3.2$ mA		0.45	V
Output High-voltage (Ports 1,2,3, ALE, PSEN)	$I_{OH} = -60$ μ A, $V_{CC} = 5V \pm 10\%$	2.4		V
	$I_{OH} = -25$ μ A	0.75 V_{CC}		V
	$I_{OH} = -10$ μ A	0.9 V_{CC}		V
	$I_{OH} = -800$ μ A, $V_{CC} = 5V \pm 10\%$	2.4		V
Output High-voltage (Port 0 in External Bus Mode)	$I_{OH} = -300$ μ A	0.75 V_{CC}		V
	$I_{OH} = -80$ μ A	0.9 V_{CC}		V
Logical 0 Input Current (Ports 1,2,3)	$V_{IN} = 0.45V$		-50	μ A
Logical 1 to 0 Transition Current (Ports 1,2,3)	$V_{IN} = 2V$, $V_{CC} = 5V \pm 10\%$		-650	μ A
Input Leakage Current (Port 0, EA)	$0.45 < V_{IN} < V_{CC}$		±10	μ A
T	Reset Pull-down Resistor	56	300	K Ω
Pin Capacitance	Test Freq. = 1 MHz, $T_2 = 25^\circ C$		10	fF
Power Supply Current	Active Mode, 12 MHz		20	mA
	Idle Mode, 12 MHz		5	mA
Power-down Mode ⁽²⁾	$V_{CC} = 0V$		100	μ A
	$V_{CC} = 3V$		40	μ A

- Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
 Maximum I_{OL} per port pin: 10 mA
 Maximum I_{OL} per 8-bit port: Port 0: 26 mA
 Ports 1, 2, 3: 15 mA
 Maximum total I_{OL} for all output pins: 71 mA
 If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
- Minimum V_{CC} for Power-down is 2V.

AT89C51

Characteristics

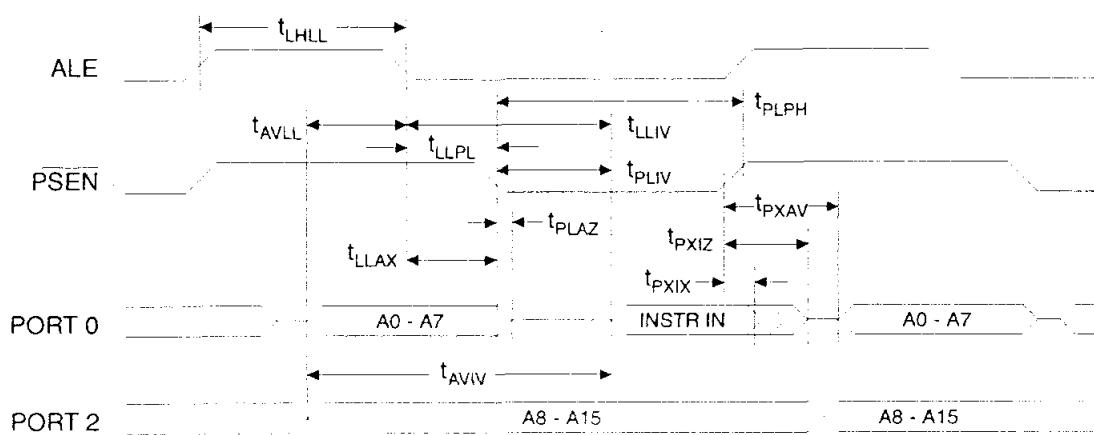
For operating conditions, load capacitance for Port 0, ALE/PROG, and PSEN = 100 pF; load capacitance for all other ports = 80 pF.

External Program and Data Memory Characteristics

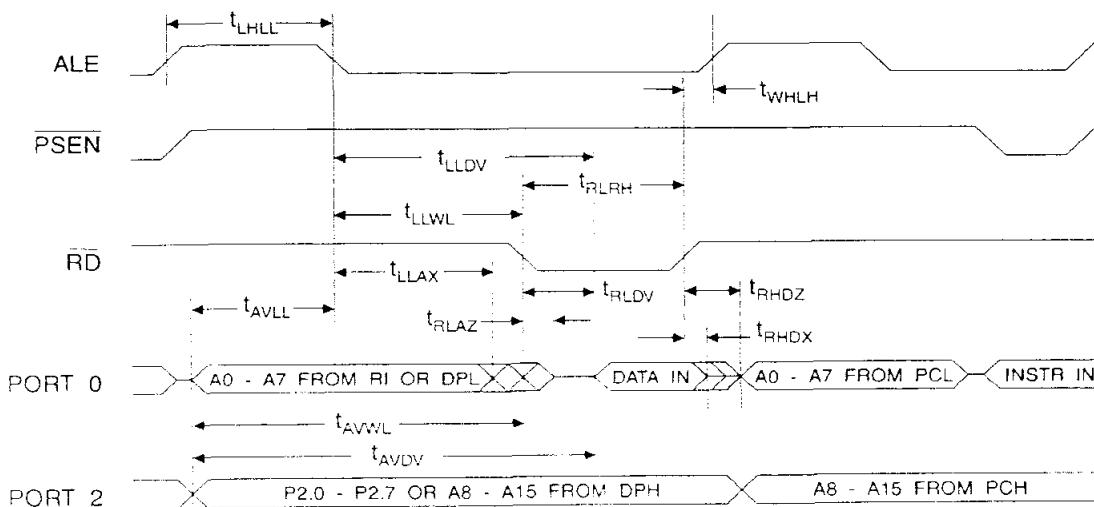
Symbol	Parameter	12 MHz Oscillator		16 to 24 MHz Oscillator		Units
		Min	Max	Min	Max	
CL	Oscillator Frequency			0	24	MHz
	ALE Pulse Width	127		$2t_{CLCL}-40$		ns
	Address Valid to ALE Low	43		$t_{CLCL}-13$		ns
	Address Hold After ALE Low	48		$t_{CLCL}-20$		ns
	ALE Low to Valid Instruction In		233		$4t_{CLCL}-65$	ns
	ALE Low to PSEN Low	43		$t_{CLCL}-13$		ns
	PSEN Pulse Width	205		$3t_{CLCL}-20$		ns
	PSEN Low to Valid Instruction In		145		$3t_{CLCL}-45$	ns
	Input Instruction Hold After PSEN	0		0		ns
	Input Instruction Float After PSEN		59		$t_{CLCL}-10$	ns
	PSEN to Address Valid	75		$t_{CLCL}-8$		ns
	Address to Valid Instruction In		312		$5t_{CLCL}-55$	ns
	PSEN Low to Address Float		10		10	ns
	RD Pulse Width	400		$6t_{CLCL}-100$		ns
	WR Pulse Width	400		$6t_{CLCL}-100$		ns
	RD Low to Valid Data In		252		$5t_{CLCL}-90$	ns
	Data Hold After RD	0		0		ns
	Data Float After RD		97		$2t_{CLCL}-28$	ns
	ALE Low to Valid Data In		517		$8t_{CLCL}-150$	ns
	Address to Valid Data In		585		$9t_{CLCL}-165$	ns
	ALE Low to RD or WR Low	200	300	$3t_{CLCL}-50$	$3t_{CLCL}+50$	ns
	Address to RD or WR Low	203		$4t_{CLCL}-75$		ns
	Data Valid to WR Transition	23		$t_{CLCL}-20$		ns
	Data Valid to WR High	433		$7t_{CLCL}-120$		ns
	Data Hold After WR	33		$t_{CLCL}-20$		ns
	RD Low to Address Float		0		0	ns
	RD or WR High to ALE High	43	123	$t_{CLCL}-20$	$t_{CLCL}+25$	ns



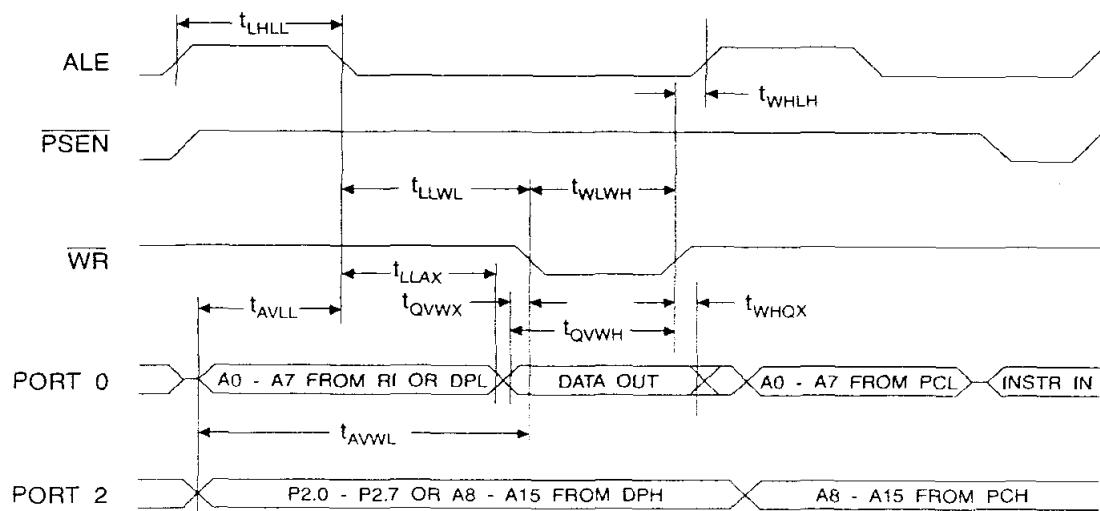
Internal Program Memory Read Cycle



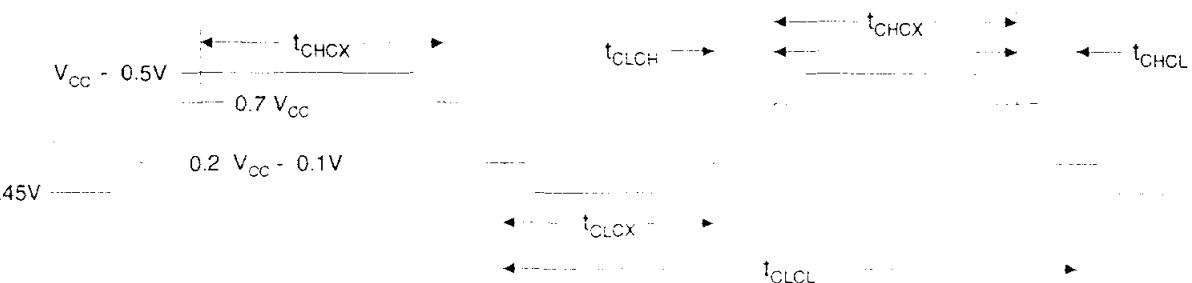
Internal Data Memory Read Cycle



External Data Memory Write Cycle



External Clock Drive Waveforms



External Clock Drive

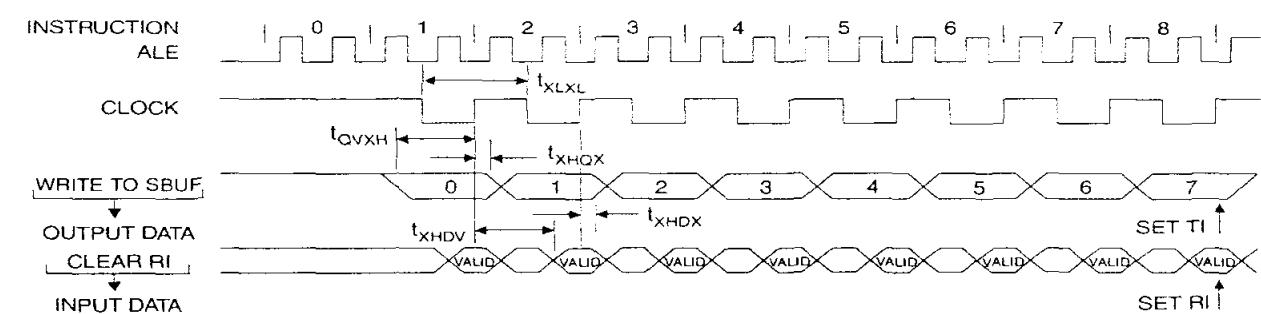
Symbol	Parameter	Min	Max	Units
CL	Oscillator Frequency	0	24	MHz
C	Clock Period	41.6		ns
x	High Time	15		ns
C	Low Time	15		ns
R	Rise Time		20	ns
F	Fall Time		20	ns

Serial Port Timing: Shift Register Mode Test Conditions

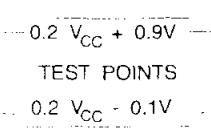
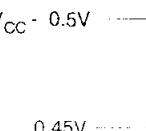
= 5.0 V ± 20%; Load Capacitance = 80 pF

mbol	Parameter	12 MHz Osc		Variable Oscillator		Units
		Min	Max	Min	Max	
XL	Serial Port Clock Cycle Time	1.0		12t _{CLCL}		μs
XH	Output Data Setup to Clock Rising Edge	700		10t _{CLCL} -133		ns
QX	Output Data Hold After Clock Rising Edge	50		2t _{CLCL} -117		ns
DX	Input Data Hold After Clock Rising Edge	0		0		ns
DV	Clock Rising Edge to Input Data Valid		700		10t _{CLCL} -133	ns

Shift Register Mode Timing Waveforms

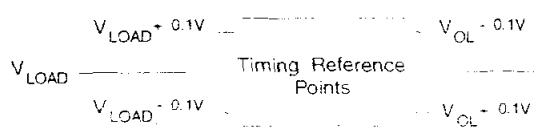


AC Testing Input/Output Waveforms⁽¹⁾



TEST POINTS

Float Waveforms⁽¹⁾



- e: 1. AC Inputs during testing are driven at $V_{CC} - 0.5V$ for a logic 1 and $0.45V$ for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

- Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when 100 mV change from the loaded V_{OH}/V_{OL} level occurs.

Ordering Information

Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
12	5V ± 20%	AT89C51-12AC	44A	Commercial (0°C to 70°C)
		AT89C51-12JC	44J	
		AT89C51-12PC	40P6	
		AT89C51-12QC	44Q	
		AT89C51-12AI	44A	Industrial (-40°C to 85°C)
		AT89C51-12JI	44J	
		AT89C51-12PI	40P6	
		AT89C51-12QI	44Q	
16	5V ± 20%	AT89C51-16AC	44A	Commercial (0°C to 70°C)
		AT89C51-16JC	44J	
		AT89C51-16PC	40P6	
		AT89C51-16QC	44Q	
		AT89C51-16AI	44A	Industrial (-40°C to 85°C)
		AT89C51-16JI	44J	
		AT89C51-16PI	40P6	
		AT89C51-16QI	44Q	
20	5V ± 20%	AT89C51-20AC	44A	Commercial (0°C to 70°C)
		AT89C51-20JC	44J	
		AT89C51-20PC	40P6	
		AT89C51-20QC	44Q	
		AT89C51-20AI	44A	Industrial (-40°C to 85°C)
		AT89C51-20JI	44J	
		AT89C51-20PI	40P6	
		AT89C51-20QI	44Q	
24	5V ± 20%	AT89C51-24AC	44A	Commercial (0°C to 70°C)
		AT89C51-24JC	44J	
		AT89C51-24PC	40P6	
		AT89C51-24QC	44Q	
		AT89C51-24AI	44A	Industrial (-40°C to 85°C)
		AT89C51-24JI	44J	
		AT89C51-24PI	40P6	
		AT89C51-24QI	44Q	

Package Type

44-lead, Thin Plastic Gull Wing Quad Flatpack (TQFP)

44-lead, Plastic J-leaded Chip Carrier (PLCC)

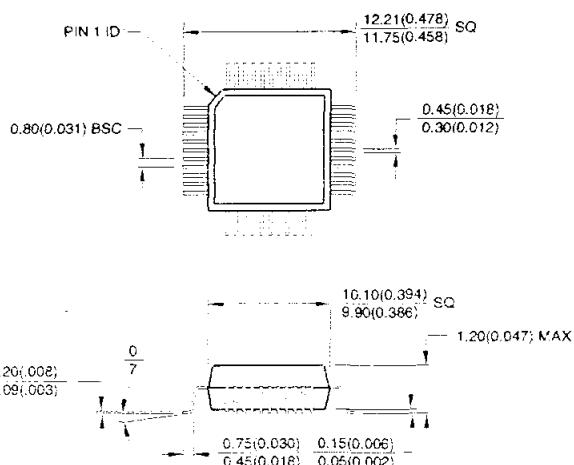
40-lead, 0.600" Wide, Plastic Dual inline Package (PDIP)

44-lead, Plastic Gull Wing Quad Flatpack (PQFP)

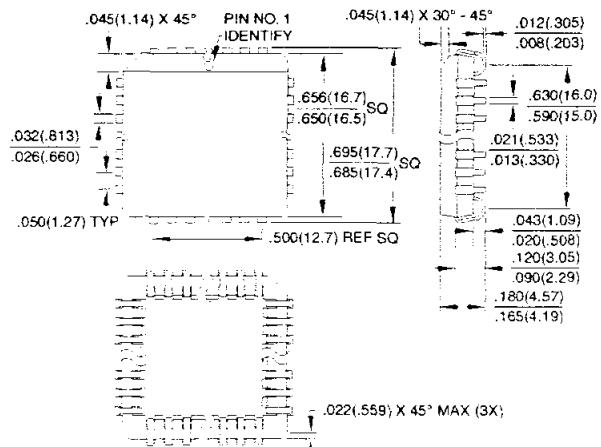


Packaging Information

4A, 44-lead, Thin (1.0 mm) Plastic Gull Wing Quad Flatpack (TQFP)
 Dimensions in Millimeters and (Inches)*
 JEDEC STANDARD MS-026 ACB

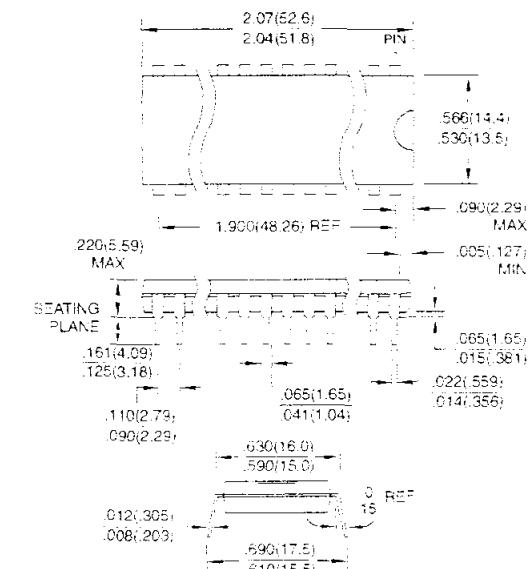


44J, 44-lead, Plastic J-leaded Chip Carrier (PLCC)
 Dimensions in Inches and (Millimeters)
 JEDEC STANDARD MS-018 AC

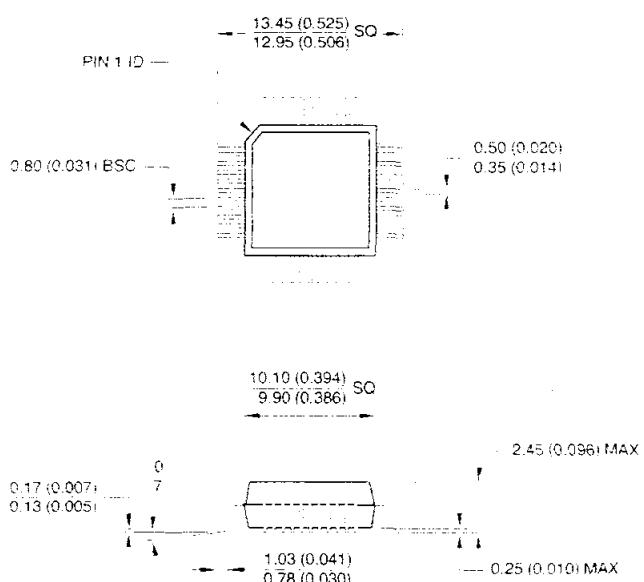


Controlling dimension: millimeters

0P6, 40-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
 Dimensions in Inches and (Millimeters)



44Q, 44-lead, Plastic Quad Flat Package (PQFP)
 Dimensions in Millimeters and (Inches)*
 JEDEC STANDARD MS-022 AB



Controlling dimension: millimeters

AT89C51



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TLC272, TLC272A, TLC272B, TLC272Y, TLC277 LinCMOS™ PRECISION DUAL OPERATIONAL AMPLIFIERS

SLOS091D – OCTOBER 1987 – REVISED JULY 2001

- Trimmed Offset Voltage:
TLC277 . . . 500 μ V Max at 25°C,
 $V_{DD} = 5$ V
- Input Offset Voltage Drift . . . Typically
0.1 μ V/Month, Including the First 30 Days
- Wide Range of Supply Voltages Over
Specified Temperature Range:
0°C to 70°C . . . 3 V to 16 V
-40°C to 85°C . . . 4 V to 16 V
-55°C to 125°C . . . 4 V to 16 V
- Single-Supply Operation
- Common-Mode Input Voltage Range
Extends Below the Negative Rail (C-Suffix,
I-Suffix types)
- Low Noise . . . Typically 25 nV/ $\sqrt{\text{Hz}}$ at
 $f = 1$ kHz
- Output Voltage Range Includes Negative
Rail
- High Input impedance . . . 10^{12} Ω Typ
- ESD-Protection Circuitry
- Small-Outline Package Option Also
Available in Tape and Reel
- Designed-in Latch-Up Immunity

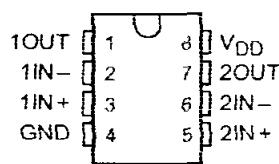
description

The TLC272 and TLC277 precision dual operational amplifiers combine a wide range of input offset voltage grades with low offset voltage drift, high input impedance, low noise, and speeds approaching those of general-purpose BiFET devices.

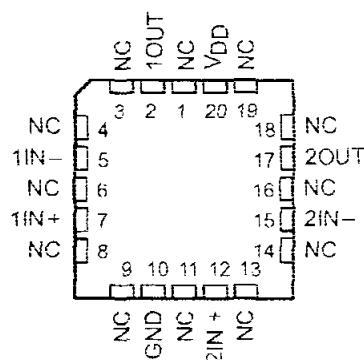
These devices use Texas Instruments silicon-gate LinCMOS™ technology, which provides offset voltage stability far exceeding the stability available with conventional metal-gate processes.

The extremely high input impedance, low bias currents, and high slew rates make these cost-effective devices ideal for applications which have previously been reserved for BiFET and NFET products. Four offset voltage grades are available (C-suffix and I-suffix types), ranging from the low-cost TLC272 (10 mV) to the high-precision TLC277 (500 μ V). These advantages, in combination with good common-mode rejection and supply voltage rejection, make these devices a good choice for new state-of-the-art designs as well as for upgrading existing designs.

D, JG, P, OR PW PACKAGE
(TOP VIEW)

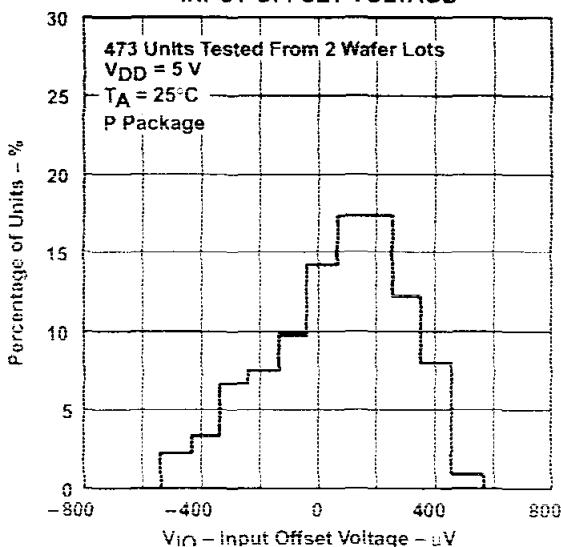


FK PACKAGE
(TOP VIEW)



NC – No internal connection

DISTRIBUTION OF TLC277
INPUT OFFSET VOLTAGE



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Products conform to specifications per the terms of Texas Instruments
standard warranty. Production processing does not necessarily include
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TLC272, TLC272A, TLC272B, TLC272Y, TLC277 LinCMOS™ PRECISION DUAL OPERATIONAL AMPLIFIERS

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description (continued)

AVAILABLE OPTIONS

T _A	V _{IOMAX} AT 25°C	PACKAGED DEVICES					CHIP FORM (Y)
		SMALL OUTLINE (D)	CHIP CARRIER (FK)	CERAMIC DIP (JG)	PLASTIC DIP (P)	TSSOP (PW)	
0°C to 70°C	500 µV	TLC277CD	—	—	TLC277CP	—	—
	2 mV	TLC272BCD	—	—	TLC272BCP	—	—
	5 mV	TLC272ACD	—	—	TLC272ACP	—	—
	10mV	TLC272CD	—	—	TLC272CP	TLC272CPW	TLC272Y
−40°C to 85°C	500 µV	TLC277ID	—	—	TLC277IP	—	—
	2 mV	TLC272BID	—	—	TLC272BIP	—	—
	5 mV	TLC272AID	—	—	TLC272AIP	—	—
	10 mV	TLC272ID	—	—	TLC272IP	—	—

The D package is available taped and reeled. Add R suffix to the device type (e.g., TLC277CDR).

In general, many features associated with bipolar technology are available on LinCMOS™ operational amplifiers without the power penalties of bipolar technology. General applications such as transducer interfacing, analog calculations, amplifier blocks, active filters, and signal buffering are easily designed with the TLC272 and TLC277. The devices also exhibit low voltage single-supply operation, making them ideally suited for remote and inaccessible battery-powered applications. The common-mode input voltage range includes the negative rail.

A wide range of packaging options is available, including small-outline and chip carrier versions for high-density system applications.

The device inputs and outputs are designed to withstand −100-mA surge currents without sustaining latch-up.

The TLC272 and TLC277 incorporate internal ESD-protection circuits that prevent functional failures at voltages up to 2000 V as tested under MIL-STD-883C, Method 3015.2; however, care should be exercised in handling these devices as exposure to ESD may result in the degradation of the device parametric performance.

The C-suffix devices are characterized for operation from 0°C to 70°C. The I-suffix devices are characterized for operation from −40°C to 85°C. The M-suffix devices are characterized for operation over the full military temperature range of −55°C to 125°C.

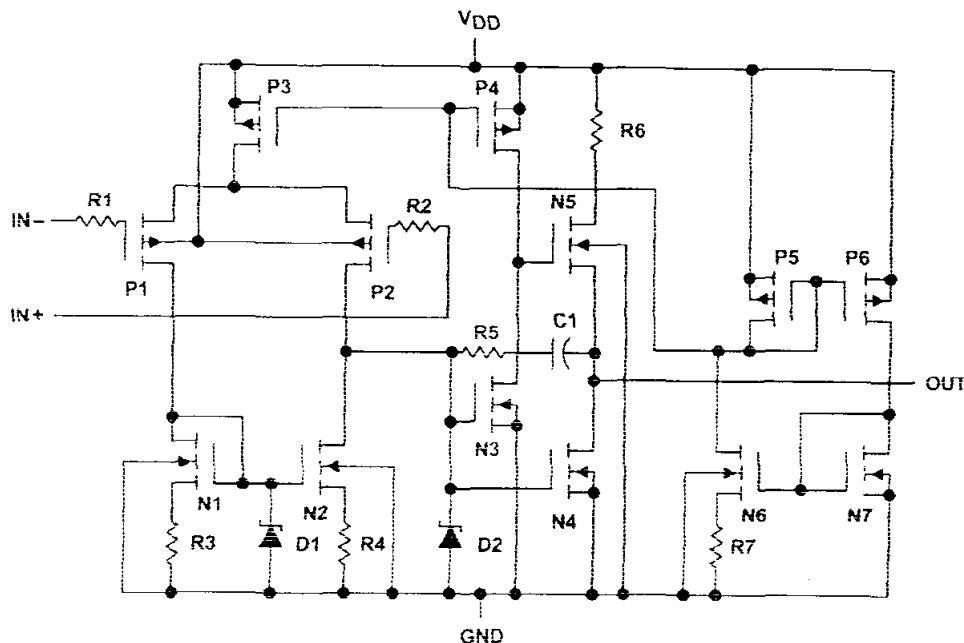


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TLC272, TLC272A, TLC272B, TLC272Y, TLC277 LinCMOS™ PRECISION DUAL OPERATIONAL AMPLIFIERS

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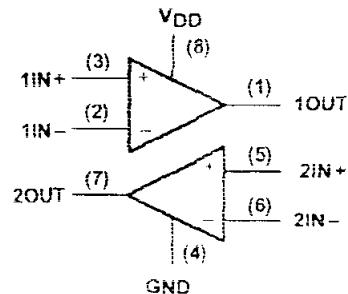
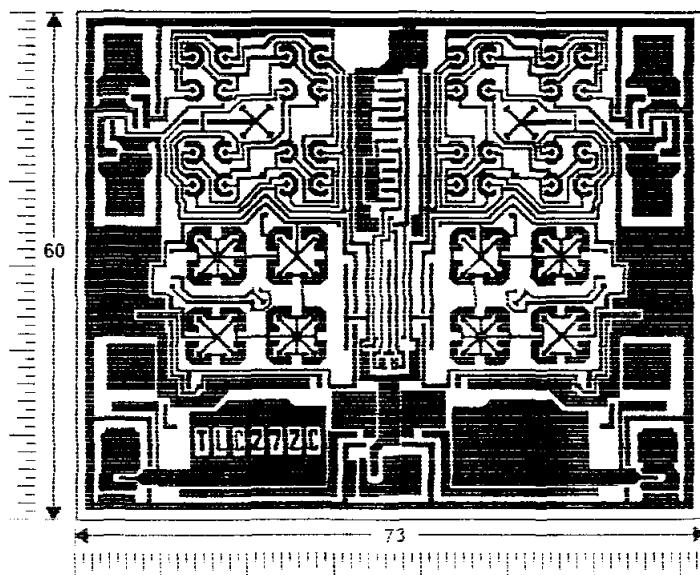
equivalent schematic (each amplifier)



TLC272Y chip information

This chip, when properly assembled, displays characteristics similar to the TLC272C. Thermal compression or ultrasonic bonding may be used on the doped-aluminum bonding pads. Chips may be mounted with conductive epoxy or a gold-silicon preform.

BONDING PAD ASSIGNMENTS



CHIP THICKNESS: 15 TYPICAL

BONDING PADS: 4 × 4 MINIMUM

$T_{jmax} = 150^\circ\text{C}$

TOLERANCES ARE $\pm 10\%$.

ALL DIMENSIONS ARE IN MILS.

PIN (4) IS INTERNALLY CONNECTED TO BACKSIDE OF CHIP.

 **TEXAS
INSTRUMENTS**

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LC272, TLC272A, TLC272B, TLC272Y, TLC277 inCMOST™ PRECISION DUAL OPERATIONAL AMPLIFIERS

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Absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{DD} (see Note 1)	18 V
Differential input voltage, V_{ID} (see Note 2)	$\pm V_{DD}$
Input voltage range, V_I (any input)	-0.3 V to V_{DD}
Input current, I_I	± 5 mA
Output current, I_O (each output)	± 30 mA
Total current into V_{DD}	45 mA
Total current out of GND	45 mA
Duration of short-circuit current at (or below) 25°C (see Note 3)	unlimited
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature, T_A : C suffix	0°C to 70°C
I suffix	-40°C to 85°C
M suffix	-55°C to 125°C
Storage temperature range	-65°C to 150°C
Case temperature for 60 seconds: FK package	260°C
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds: D, P, or PW package	260°C
Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds: JG package	300°C

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to network ground.
 2. Differential voltages are at $IN+$ with respect to $IN-$.
 3. The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded (see application section).

DISSIPATION RATING TABLE

PACKAGE	TA ≤ 25°C POWER RATING	DERATING FACTOR ABOVE TA = 25°C	TA = 70°C POWER RATING	TA = 85°C POWER RATING	TA = 125°C POWER RATING				
						C SUFFIX	I SUFFIX		
						MIN	MAX	M SUFFIX	UNIT
D	725 mW	5.8 mW/°C	464 mW	377 mW	N/A				
FK	1375 mW	11 mW/°C	880 mW	715 mW	275 mW				
JG	1050 mW	8.4 mW/°C	672 mW	546 mW	210 mW				
P	1000 mW	8.0 mW/°C	640 mW	520 mW	N/A				
PW	525 mW	4.2 mW/°C	336 mW	N/A	N/A				

Recommended operating conditions

		C SUFFIX		I SUFFIX		M SUFFIX		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
Supply voltage, V_{DD}		3	16	4	16	4	16	V
Common-mode input voltage, V_{IC}	$V_{DD} = 5$ V	-0.2	3.5	-0.2	3.5	0	3.5	V
	$V_{DD} = 10$ V	-0.2	8.5	-0.2	8.5	0	8.5	
Operating free-air temperature, T_A		0	70	-40	85	-55	125	°C



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TLC272, TLC272A, TLC272B, TLC272Y, TLC277
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electrical characteristics at specified free-air temperature, $V_{DD} = 5$ V (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TA†	TLC272C, TLC272AC, TLC272BC, TLC277C			UNIT
			MIN	TYP	MAX	
V _{IO} Input offset voltage	TLC272C $V_O = 1.4$ V, $R_S = 50 \Omega$	$V_{IC} = 0$, $R_L = 10 k\Omega$	25°C	1.1	10	mV
			Full range		12	
	TLC272AC $V_O = 1.4$ V, $R_S = 50 \Omega$	$V_{IC} = 0$, $R_L = 10 k\Omega$	25°C	0.9	5	
			Full range		6.5	
TLC272BC TLC277C	TLC272BC $V_O = 1.4$ V, $R_S = 50 \Omega$	$V_{IC} = 0$, $R_L = 10 k\Omega$	25°C	230	2000	μ V
			Full range		3000	
	TLC277C $V_O = 1.4$ V, $R_S = 50 \Omega$	$V_{IC} = 0$, $R_L = 10 k\Omega$	25°C	200	500	
			Full range		1500	
α_{VIO} Temperature coefficient of input offset voltage			25°C to 70°C		1.8	μ V/°C
I _{IO} Input offset current (see Note 4)	$V_O = 2.5$ V, $V_{IC} = 2.5$ V	25°C		0.1	60	pA
			70°C	7	300	
		25°C		0.6	60	
			70°C	40	600	
V _{ICR} Common-mode input voltage range (see Note 5)		25°C	-0.2 to 4	-0.3 to 4.2		V
		Full range	-0.2 to 3.5			
V _{OH} High-level output voltage	$V_D = 100$ mV, $R_L = 10 k\Omega$	25°C	3.2	3.8		V
		0°C	3	3.8		
		70°C	3	3.8		
V _{OL} Low-level output voltage	$V_D = -100$ mV, $I_{OL} = 0$	25°C	0	50		μ V
		0°C	0	50		
		70°C	0	50		
A _{VD} Large-signal differential voltage amplification	$V_O = 0.25$ V to 2 V, $R_L = 10 k\Omega$	25°C	5	23		μ V/mV
		0°C	4	27		
		70°C	4	20		
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$	25°C	65	80		dB
		0°C	60	84		
		70°C	60	85		
K _{SVR} Supply-voltage rejection ratio ($\Delta V_{DD}/\Delta V_{IO}$)	$V_{DD} = 5$ V to 10 V, $V_O = 1.4$ V	25°C	65	95		dB
		0°C	60	94		
		70°C	60	96		
I _{DD} Supply current (two amplifiers)	$V_O = 2.5$ V, No load	25°C	1.4	3.2		mA
		0°C	1.6	3.6		
		70°C	1.2	2.6		

† Full range is 0°C to 70°C.

NOTES: 4. The typical values of input bias current and input offset current below 5 pA were determined mathematically.
 5. This range also applies to each input and V_{IC} duty.



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TLC272, TLC272A, TLC272B, TLC272Y, TLC277
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electrical characteristics at specified free-air temperature, $V_{DD} = 10\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T_{AT}^{\dagger}	TLC272C, TLC272AC, TLC272BC, TLC277C			UNIT
			MIN	TYP	MAX	
V_{IO} Input offset voltage	TLC272C $V_O = 1.4\text{ V},$ $R_S = 50\text{ }\Omega,$ $V_{IC} = 0,$ $R_L = 10\text{ k}\Omega$	25°C	1.1	10		mV
		Full range			12	
	TLC272AC $V_O = 1.4\text{ V},$ $R_S = 50\text{ }\Omega,$ $V_{IC} = 0,$ $R_L = 10\text{ k}\Omega$	25°C	0.9	5		
		Full range			6.5	
	TLC272BC $V_O = 1.4\text{ V},$ $R_S = 50\text{ }\Omega,$ $V_{IC} = 0,$ $R_L = 10\text{ k}\Omega$	25°C	290	2000	μV	
		Full range			3000	
	TLC277C $V_O = 1.4\text{ V},$ $R_S = 50\text{ }\Omega,$ $V_{IC} = 0,$ $R_L = 10\text{ k}\Omega$	25°C	250	800		
		Full range			1900	
α_{VIO}	Temperature coefficient of input offset voltage	25°C to 70°C		2		$\mu\text{V}/\text{°C}$
I_{IO} Input offset current (see Note 4)	$V_O = 5\text{ V},$ $V_{IC} = 5\text{ V}$	25°C	0.1	60		pA
		70°C	7	300		pA
		25°C	0.7	60		pA
		70°C	50	600		pA
V_{ICR} Common-mode input voltage range (see Note 5)		25°C	-0.2 to 9	-0.3 to 9.2		V
		Full range	-0.2 to 8.5			V
		25°C	8	8.5		
		0°C	7.8	8.5		V
V_{OH} High-level output voltage	$V_{ID} = 100\text{ mV},$ $R_L = 10\text{ k}\Omega$	70°C	7.8	8.4		
		25°C	0	50		
		0°C	0	50		mV
		70°C	0	50		
V_{OL} Low-level output voltage	$V_{ID} = -100\text{ mV},$ $I_{OL} = 0$	25°C	0	50		
		0°C	0	50		
		70°C	0	50		
		25°C	10	36		
A_{VD} Large-signal differential voltage amplification	$V_O = 1\text{ V to }6\text{ V},$ $R_L = 10\text{ k}\Omega$	0°C	7.5	42		V/mV
		70°C	7.5	32		
		25°C	65	85		
$CMRR$ Common-mode rejection ratio	$V_{IC} = V_{ICR\min}$	0°C	60	88		dB
		70°C	60	88		
		25°C	65	95		
$KSVR$ Supply-voltage rejection ratio ($\Delta V_{DD}/\Delta V_O$)	$V_{DD} = 5\text{ V to }10\text{ V},$ $V_O = 1.4\text{ V}$	0°C	60	94		dB
		70°C	60	96		
		25°C	1.9	4		
I_{DD} Supply current (two amplifiers)	$V_O = 2.5\text{ V},$ No load	0°C	2.3	4.4		mA
		70°C	1.8	3.4		

† Full range is 0°C to 70°C.

NOTES: 4. The typical values of input bias current and input offset current below 5 pA were determined mathematically.

5. This range also applies to each input individually.



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